承 認 書

SPECIFICATION FOR APPROVAL

CUSTOMER:	STD
DESCRIPTION:	WIRE WOUND CHIP INDUCTOR
PART NO:	MWI0805LD-TIA系列
CUST. PART NO:	
REV. NO.	A0

DRAWING		
PREPARED	CHECKED	APPROVED
Yu	Lu	Zeng
DATE:	2023/10/10	

CUSTOMER APPROVE

铭易轩电子科技有限公司

Ming Yixuan Electronic Technology Co., LTD

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Specifications subjectto change withoutnotice.Please confirm according to our companyfor latestinformation

网址: http://www.dgmingyixuan.com

铭易轩电子 SPECIFICATION FOR APPROVAL

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MODIFY RECORD 变更履历

Date	Rev. No.	Change Content	Prepared	Approved
2023/10/10	A0	New issue	Yu	Zeng

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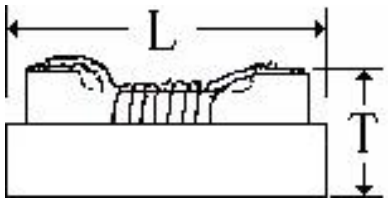
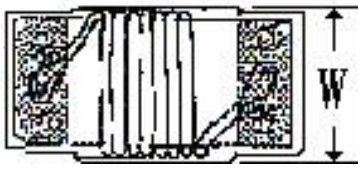
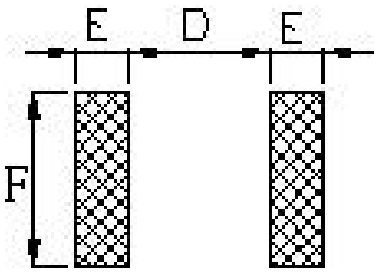
1. SHAPE & DIMENSION (UNIT:mm)



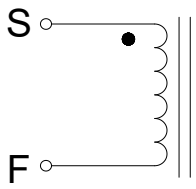




Recommended patterns

L	W	T	E	F	D
2.4 Max.	1.73 Max.	1.52 Max.	1.02 Typ.	1.78 Typ.	0.76 Typ.

2. SCHEMATIC



3. PART NUMBERING SYSTEM

MWI	xxx	LD	xxx	M	S	T	-	HF
1	2	3	4	5	6	7		8

1 PRODUCT SYMBOL（产品代号）

2 DIMENSIONS （规格尺寸）

3 MATERIAL （芯片类型）

4 INDUCTANCE（电感量）

5 TOLERANCE（公差）：K±10%；M±20%

6 TERMINAL （端电极材料）： S-锡端头

7 PACKAGING （包装方式）：T-编带盘装；B –散装

8 E.P.（环保）：LF—Lead Free HF—Halogen Free FP—Red Phosphor Free

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4. ELECTRICAL CHARACTERISTICS

No.	Part Number	L	Freq	Q	SRF	Rdc±30%	Isat	Irms
		(uH)	(MHz)	(Typ.)	(MHz)Typ.	(Ω)	(mA)Typ.	(mA)Typ.
1	MWI0805LD1R0MST-TIA-HF	1	1	12	250	0.14	1100	1200
2	MWI0805LD2R2MST-TIA-HF	2.2	1	12	100	0.18	750	900
3	MWI0805LD4R7MST-TIA-HF	4.7	1	12	50	0.32	530	550
4	MWI0805LD8R2MST-TIA-HF	8.1	1	12	35	0.50	430	460
5	MWI0805LD100MST-TIA-HF	10	1	12	35	0.55	420	450

Test remarks

(1). All test data is referenced to 25 ℃ ambient.

(2). Isat: DC current at which inductance drops approximate 30% from its value without current,

Irms: DC current that causes the temperature rise (△T ≦40℃) from 25℃ ambient.

5. GENERAL SPECIFICATION

(1). Operating temp.: -40℃ ~ +85℃ (Including self-generated heat).

(2). Storage temp.: -10℃ ~ +40℃ R.H.:60% Max.

(3). Moisture sensitivity level (MSL) 1

(4). Recommended products should be used within 12 months from the date of delivery

(5). The part temperature (ambient + temp rise) should not exceed 85 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

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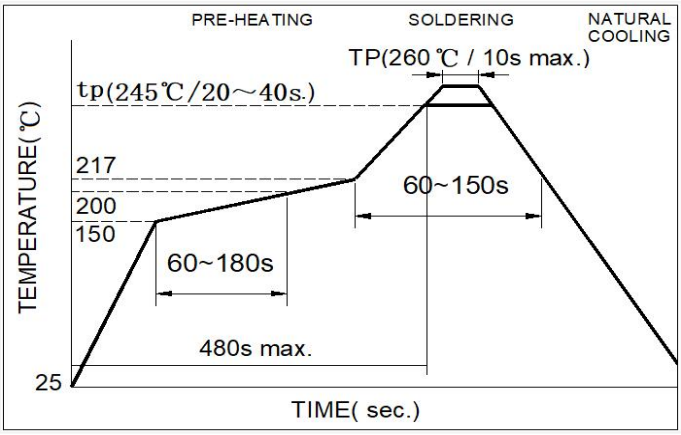
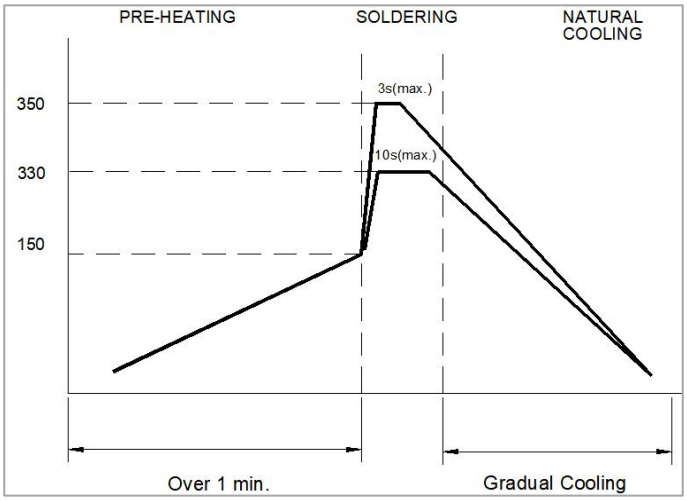
6. SOLDERING CONDITIONS

Figure 1. Re-flow Soldering (Lead Free)



Note：
Preheat circuit and products to 150℃
260℃ tip temperature (Max)
Reflow times: no more than 2 times
Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

Figure 2. Hand Soldering





Note：
Use a 20 watt soldering iron with tip diameter of 1.0mm
Limit soldering time to 3 sec.

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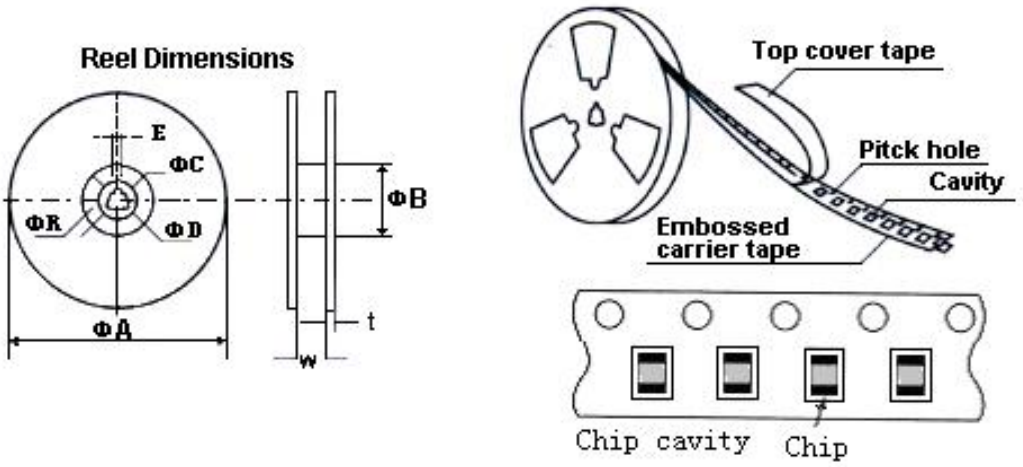
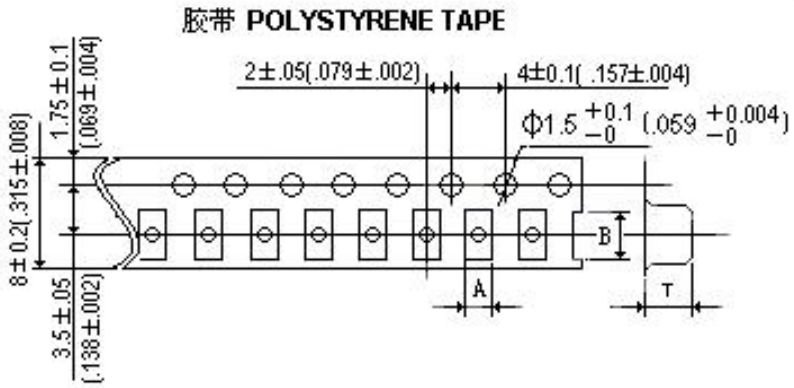
7. PACKAGE SPECIFICATION（unit: mm）

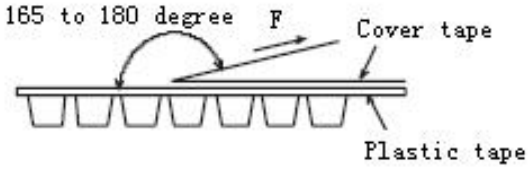




Peeling off force

Pull strength
0402～1210:20g～80g

Speed of peeling off:
300mm/min±10%



胶带		A	B	T
	0805	1.85	2.4	1.45

Type	ΦA	ΦB	ΦC	ΦD	E	W	t
0805	178	60	13	21	2	8.4	2

包装数量(PACKAGING QUANTITY)：2000Pcs/盘

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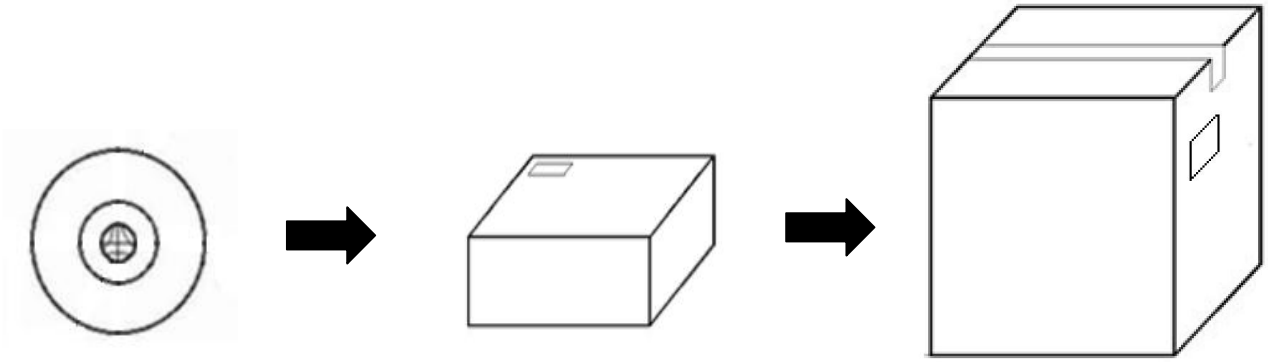
8. Package Specifications

Inside Box And Outside Carton



卷轴数量	→	内盒包装数量	→	外箱包装数量
每卷:2000PCS		**每盒四盘，共8000 PCS**		**小箱6盒，共48000 PCS**
				中箱8盒，共64000 PCS
				大箱10盒，共80000 PCS

内盒包装尺寸	→	外箱包装尺寸
20.3*19.3*5.5cm		**小箱，40.6*23*19.7cm**
		中箱，41*22*26cm
		大箱，41*22*33cm

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